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CENTRAL FAX CENTER

AI-TECH-16B

AUG 18 2005

PATENT APPLICATION
Serial No. 10/774,882**AMENDMENT TO THE ABSTRACT**

Please amend the Abstract by deleting the present Abstract and substituting the following replacement Abstract therefor:

A molecularly flexible dielectric electronic substrate for receiving an electronic device has a modulus of elasticity less than about 500,000 psi. The molecularly flexible dielectric substrate comprises one or more sheets or layers of a molecularly flexible dielectric adhesive having a modulus of elasticity less than about 500,000 psi and having patterned metal foil electrical conductors thereon. The molecularly flexible dielectric adhesive may have a low glass transition temperature and the ability to withstand soldering.